

*Examiner's Copy*

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TI **Silver**-containing **tin**-base solver  
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SO Jpn. Kokai Tokkyo Koho, 5 pp.  
CODEN: JKXXAF  
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PI	JP 06269982	A2	19940927	JP 1993-58544	19930318
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AB A solver contains **Ag** 5-20, **Sn** 70-90, **Cu** 0.05-10, **Pd** 0.05-2, and **In** and/or **Ga** 0.05-5%. The **solder** has high corrosion resistance and elec. and thermal cond. and is suitable for elec. industry.